

Automotive Reliability Qualification Plan for LFCSP Package at Amkor Philippines(ATP)

QUALIFICATION PLAN			
Test	Conditions	Sample Size	Expected Completion Date
Temperature/Humidity/Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	April 2014
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	April 2014
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	April 2014
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	1 x 18	April 2014

*These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Soak: Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C. TCT samples will be wire-pull test after 500 cycles. Preconditioned per JEDEC/IPC J-STD-020.

BILL OF MATERIALS					
Generic	Material List	Wire Size	DIE ATTACH EPOXY	MOLD COMPOUND	
				FROM	TO
ADA4830-1	ADA4830-1BCPZ-R7 ADA4830-1WBCPZ-R7	0.8 mil	ABLESTIK 8290	SUMITOMO G770	SUMITOMO G700
ADA4830-2	ADA4830-2BCPZ-R7 ADA4830-2WBCPZ-R7				